

PC55H10 V2 **Product Specification**



Approval Sheet

PC55H10 V2
Product Specification



Product	White SMD LED
Part Number	PC55H10 V2
Issue Date	2015/12/21



Feature

- \checkmark White SMD LED (L x W x H) of 5.8 x 5.2 x 0.7 mm
- ✓ ANSI binning
- ✓ Dice Technology : InGaN
- ✓ Qualified according to JEDEC moisture sensitivity Level 3
- ✓ Environmental friendly; RoHS compliance
- ✓ Packing: 500 pcs/reel

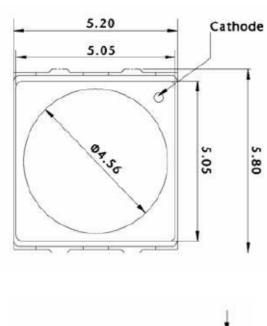
Applications

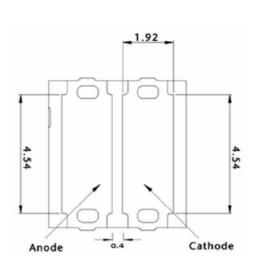
- ✓ MR16, GU10
- ✓ General lighting
- ✓ Outdoor lighting

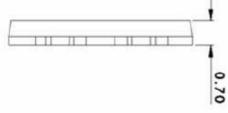


Outline Dimension

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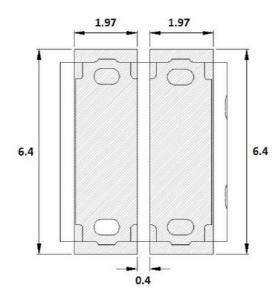




Unit: mm,

Tolerance: ±0.1mm

■ Recommended Soldering Pad





Performance

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■ Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage ⁽¹⁾	V_{F}		11.1	12.3	13.5	V
Color Rendering Index ⁽²⁾	Ra		80	-	-	-
Color Rendering Index ⁽³⁾	R9	$I_F = 450 \text{ mA}$	0			
View Angle	θ		-	120	-	deg
Thermal Resistance ⁽⁴⁾	R _{th}		-	4	-	°C/W

- (1) The Forward Voltage tolerance is ±0.1V
- (3) The R9 is measured at Ta=85 $^{\circ}$ C and tolerance is ±6.
- (4) Thermal resistance is calculated from junction to solder

■ Luminous Flux (Ta=25°C)

CCT	Condition	Rank	Тур.	Unit
2600K~4000K	1 450 mA	GQ,GR	700	lm
5000K~7000K	$I_F = 450 \text{ mA}$	GR,GS	740	lm

^{*} The luminous flux tolerance is ± 7%

Absolute Maximum Ratings

Parameter	Symbol	value	Unit
DC Forward Current ⁽¹⁾	IF	720	mA
Power Dissipation	PD	8.7	W
Pulse Forward Current (2)	IFP	1080	mA
Storage Temperature	Tstg	-40 ~ 100	οС
Operating Temperature	Topr	-40 ~ 100	оС
Junction Temperature	TJ	125	оС
Assembly Temperature	-	260 (max. 10sec)	°C

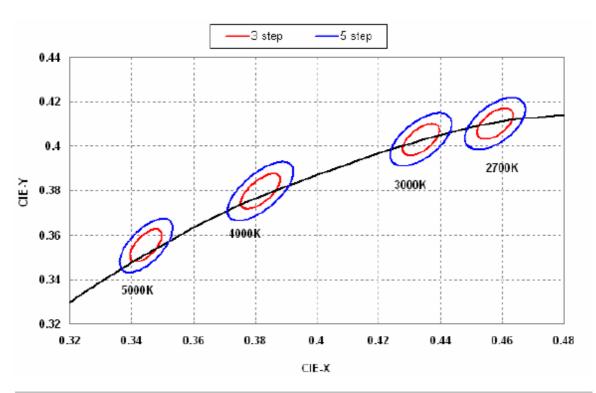
- (1) Proper current rating must be observed to maintain junction temperature below maximum at all time
- (2) IFP Condition: Duty 1/10, Pulse within 10msec



Binning

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■ Chromaticity Coordinates(Ta=85°C)



Items	2700K 3-Step	3000K 3-Step	4000K 3-Step	5000K 3-Step
items	(273S)	(303S)	(403S)	(503S)
Center Point, Cx	0.4578	0.4338	0.3818	0.3447
Center Point, Cy	0.4101	0.4030	0.3797	0.3553
Major Axis, a	0.0081	0.0083	0.0093	0.0082
Minor Axis, b	0.0042	0.0040	0.0040	0.0035
Rotation Angle	53.7	53.2	53.7	59.6

Items	2700K 5-Step (275S)	3000K 5-Step (305S)	4000K 5-Step (405S)	5000K 5-Step (505S)
Center Point, Cx	0.4578	0.4338	0.3818	0.3447
Center Point, Cy	0.4101	0.4030	0.3797	0.3553
Major Axis, a	0.0135	0.01390	0.0156	0.0137
Minor Axis, b	0.0070	0.00680	0.0040	0.0059
Rotation Angle	53.7	53.2	53.7	59.6



■ Bin code definition

V _F Rank	Luminous Flux Rank	CIE Rank
273S	GP	Y

V _F Rank	Condition	Min.	Max.
Υ	$I_F = 450 \text{mA}$	11.1	13.5

Luminous Flux Rank	Condition	Min.	Max.
GP	I _F = 450 mA	550	600
GQ		600	660
GR		660	726
GS		726	799

Note:

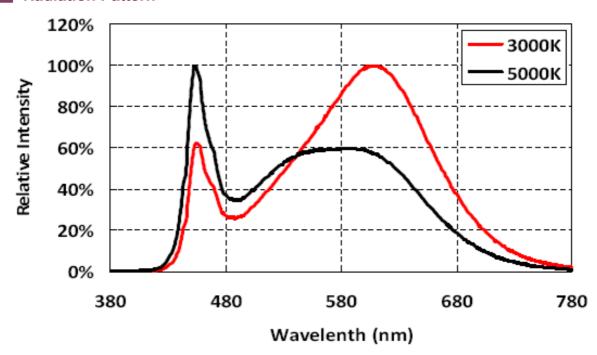
- (1) Correlated color Temperature is derived from the CIE 1931Chromaticity diagram
- (2) CIE Measurement tolerance is ± 0.005
- (3) The luminous flux tolerance is ±7%
- (4) The Forward Voltage tolerance is ±3%



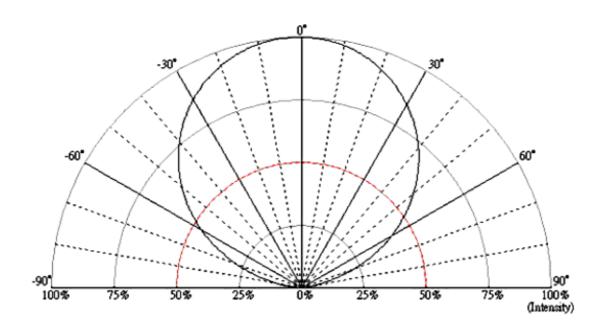
Characteristics

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Radiation Pattern

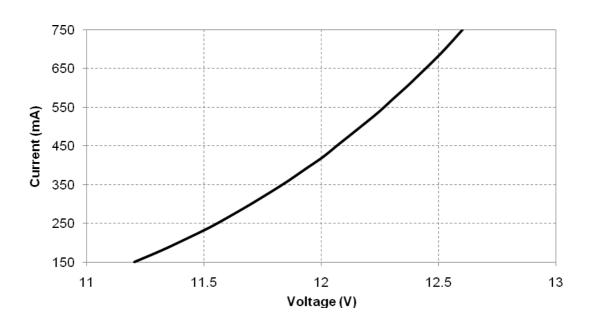


Radiation Pattern

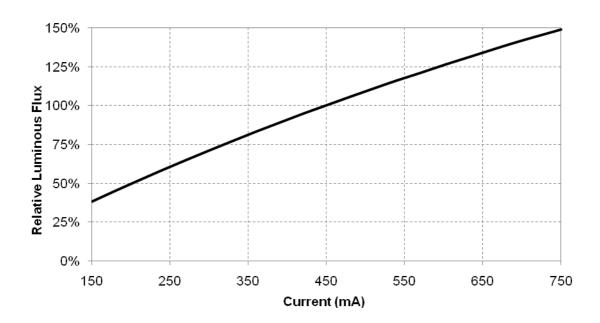




Forward Voltage vs. Forward Current

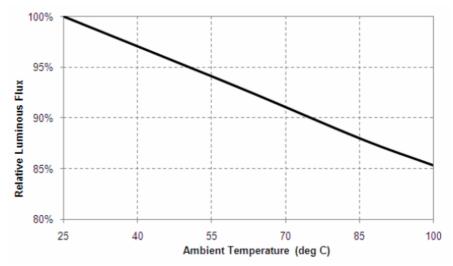


Forward Current vs. Relative Luminosity

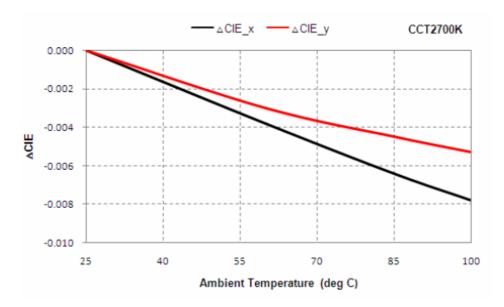




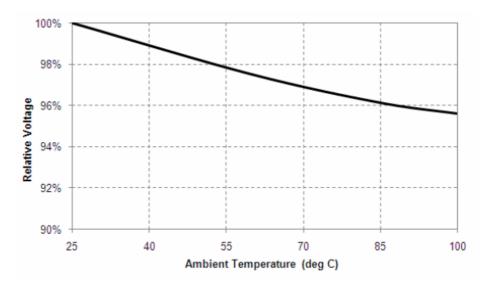
Relative Luminous Intensity vs. Ambient Temperature



■ Chromaticity vs. Ambient Temperature



Relative VF vs. Ambient Temperature





Reliability

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Reliability test

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Item	Condition	Time/Cycle	
Steady State Operating Life of Low	40°C Operating	1000 Use	
Temperature -40°C	-40°C Operating	1000 Hrs	
Steady State Operating Life of High	60°C Operating	1000 Use	
Temperature 60°C	60°C Operating	1000 Hrs	
Steady State Operating Life of High	95°C Operating	1000 Uro	
Temperature 85°C	85°C Operating	1000 Hrs	
Steady State Operating Life of High	105°C Operating	1000 Uro	
Temperature 100°C	105 C Operating	1000 Hrs	
Low temperature storage -40°C	-40°C Storage	1000 Hrs	
High temperature storage 100°C	105°C Storage	1000 Hrs	
Steady State Operating Life of High	60°C/00°/ Operating	1000 Ure	
Humidity Heat 60°C90%	60°C/90% Operating	1000 Hrs	
Resistance to soldering heat on	pre-store@60°C, 60%RH for 52hrs Tsld	2 Times	
PCB (JEDEC MSL3)	max.=260°C 10sec	3 Times	
Thermal shock	-40°C/20minr ~5minr ~	200 Cyclos	
THEITIAI SHOCK	100°C/20min	300 Cycles	

Judgment Criteria

Item	Symbol	Test Condition	Judgment Criteria
Forward Voltage	Vf	150mA	ΔVf < 10 %
Luminous Flux	lv	150mA	Δlv < 30 %

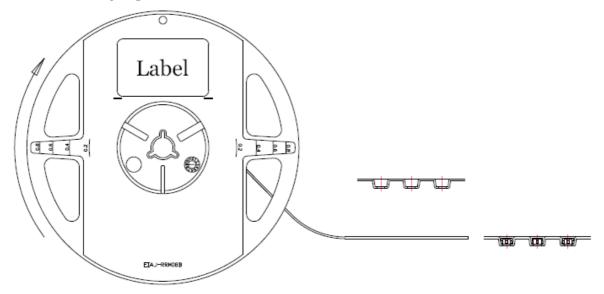


Packing

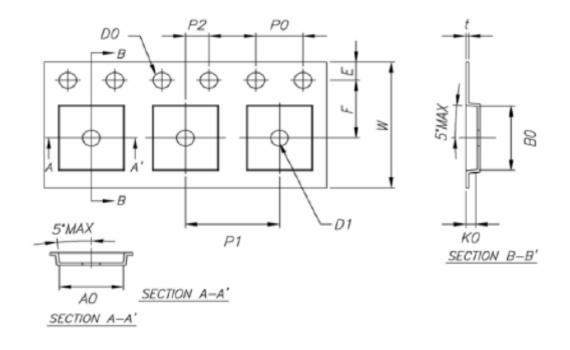
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Label

Carrier Taping





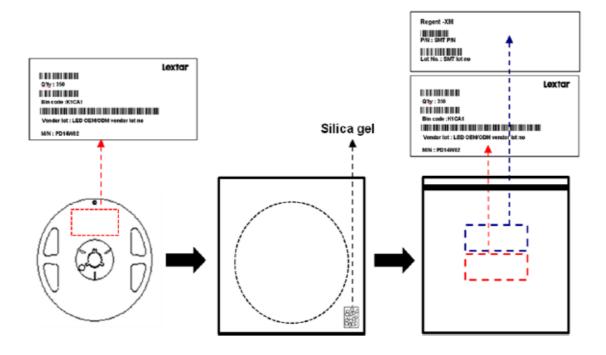


PS: unit: mm

Notice:

- 1. 10 Sprocket hole pitch cumulative tolerance is ± 0.20 mm.
- 2. Carrier camber shall be not more than 1mm per 100mm through a length of 250mm.
- 3. Ao & Bo measured on a place in the middle of the corner radii.
- 4. Ko measured from a place on the inside bottom of the pocket to top surface of carrier.
- 5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
- 6. Surface resisivity 10⁴ ~10⁸ ohm/sq.

Shield Bag Taping

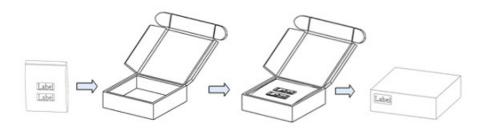




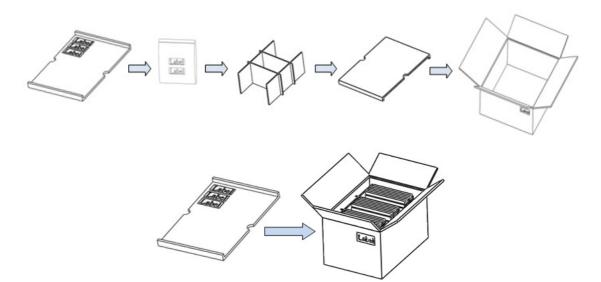
Packing Box

Туре	Large Box		Medium Box		Small Box	
Dimension	541X511X276mm		385X303X260mm		283X235x70mm	
Maximum Reels	7"X12mm Reel	64/R	7"X12mm Reel	21/R	7"X12mm Reel	4/R
Minimum Reels	7"X12mm Reel	32/R	7"X12mm Reel	9/R	7"X12mm Reel	1/R

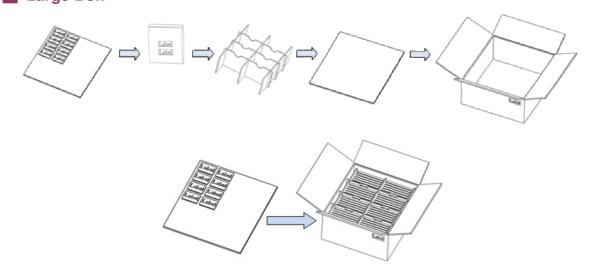
Small Box



Medium Box



Large Box





Precautions

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Safety Precautions

- The LED light output is too strong for human eyes without shield. Prevent eye contact directly more than seconds.
- Ensure operating under maximum rating.

Storage

- Before opening the package, the LEDs should storage under 30℃, 60% RH.
- After opening the package bag, the LEDs should be keep under 30℃, 60% RH.
 Recommend to use within 168 hrs. If unused LEDs remain, suggest to store into moisture proof bag or original package bag with moisture absorbent material such as silica gel.
 Reseal well is necessary.
- If the product exceeded the storage period or the moisture absorbent material faded away, baking treatment should be done by following conditions.
 Bake condition: 60℃, 12hours (One time only).

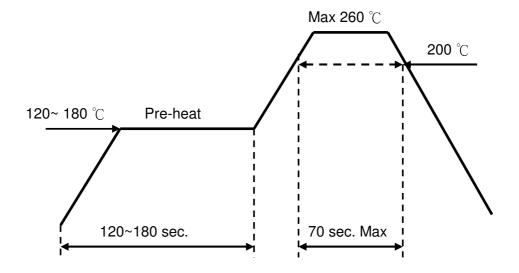
Soldering Notice and Conditions

- When soldering LEDs,
- Do not solder/reflow the same LED over two times.
- Recommend soldering conditions:

Reflow soldering: Pre-heat 150 $^{\circ}$ C max , 180 sec. max.

Peak 260 °C max, 10 sec. max.

• Reflow temperature profile as below: (lead-free solder)





- When soldering, don't put stress on the LEDs
- After LEDs have been soldered, strongly recommend not to repair to keep the LEDs performance.

Static Electricity

- LED package is extremely sensitive to static electricity. It's recommended that
 anti-electrostatic glove and wrist band is necessary when handling the LEDs. All devices
 are also be grounded properly as well.
- Protection devices design should be considered in the LED driving circuit.

Cleaning

- If washing is required, recommend to use alcohol as a solvent.
- Recommend to avoid cleaning the LEDs by ultrasonic. If necessary, pre-test the LED is necessary to confirm whether any damage occur after the process.



Revision History

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Date	Contents	Writer	Approved
2016.01.07	New version	Kenis Hung	Berris Huang

Smart Lighting Amazing Life

Lextar Electronics Corp. is the leading LED (Light Emitting Diode)
maker integrating upper stream epitaxial, middle stream chip, and downstream package,
SMT and LED lighting applications. Founded in May, 2008, Lextar is a subsidiary of AU Optronics,
the leading TFT-LCD and solar PV manufacturer. Lextar's product applications include lighting and LCD backlight.
Lextar's manufacturing sites include Hsinchu and Chunan in Taiwan, and Suzhou in China.
The company turnover in 2010 is 266 million USD.